



SSC8029GS6A

P-Channel Enhanced MOSFET

➤ Features

VDS	VGS	RDSON Typ.	ID
-20V	±12V	18mR@-4V5	-7A
		22mR@-2V5	
		29mR@-1V8	

➤ Description

This device is P-Channel enhancement MOSFET. Uses advanced trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

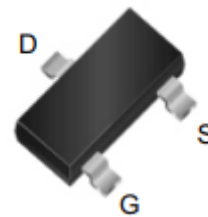
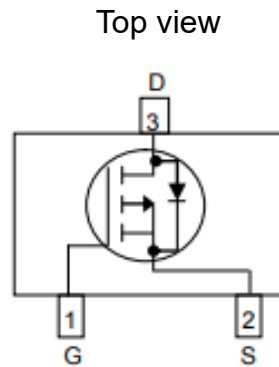
➤ Applications

- DC/DC conversion
- Power management in portable
- Load/Power Switching for portable device

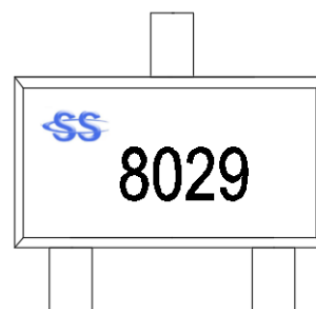
➤ Ordering Information

Device	Package	Shipping
SSC8029GS6A	SOT-23-3L	3000/Reel

➤ Pin configuration



SOT-23-3L



Marking



➤ **Absolute Maximum Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	-20	V
V_{GSS}	Gate-to-Source Voltage	± 12	V
I_D	Continuous Drain Current ^a	-7	A
I_{DM}	Pulsed Drain Current ^b	-29	A
P_D	Power Dissipation ^c	2.7	W
P_{DSM}	Power Dissipation ^a	1.3	W
T_J	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a		96	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		46	

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with $T_A=25^{\circ}\text{C}$.The value in any given application depends on the user is specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

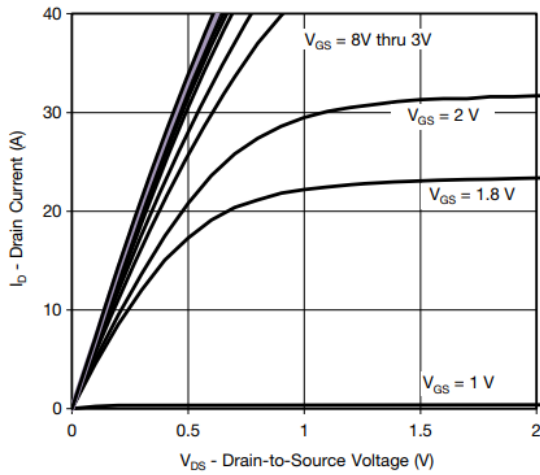


➤ **Electronics Characteristics**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

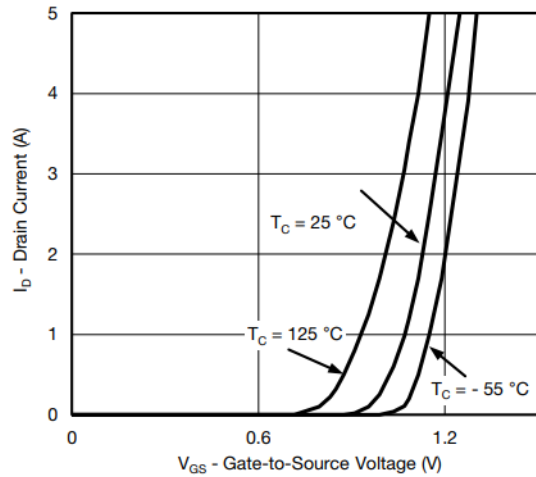
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.6	-1	V
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=-4.5V, I_D=-5A$		18	24	mR
		$V_{GS}=-2.5V, I_D=-3A$		22	29	
		$V_{GS}=-1.8V, I_D=-2A$		29	37	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-16V, V_{GS}=0V$			-1	μA
I_{GSS}	Gate-Source leak current	$V_{GS}=\pm 12V, V_{DS}=0V$			± 100	nA
G_{FS}	Transconductance	$V_{DS}=-5V, I_D=-6A$		25		S
V_{SD}	Forward Voltage	$V_{GS}=0V, I_S=-2A$			1.3	V
C_{iss}	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V,$ $f=1MHz$		1980		pF
C_{oss}	Output Capacitance			210		
C_{rss}	Reverse Transfer Capacitance			189		
$T_{D(ON)}$	Turn-on delay time			35		
T_r	Rise time	$V_{GS}=-4.5V, R_L=3R$		30		ns
$T_{D(OFF)}$	Turn-off delay time	$V_{DS}=-10V, R_G=6R$		133		
T_f	Fall time			87		
Q_G	Total Gate Charge			22		
Q_{GS}	Gate to Source Charge	$V_{GS}=-4.5V, V_{DS}=-10V$ $I_D=-6.6A$		4		nC
Q_{GD}	Gate to Drain Charge			5		



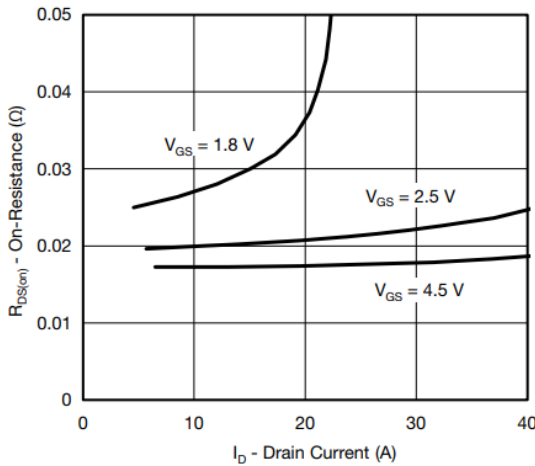
➤ **Typical Characteristics** ($T_A=25^\circ\text{C}$ unless otherwise noted)



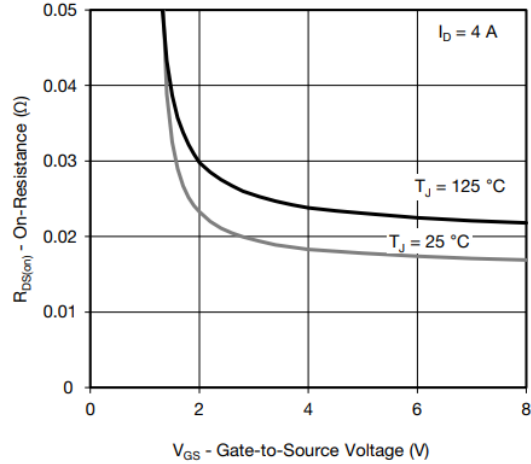
Output Characteristics



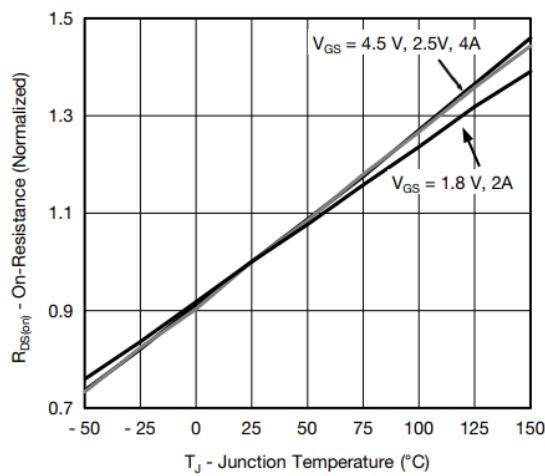
Transfer Characteristics



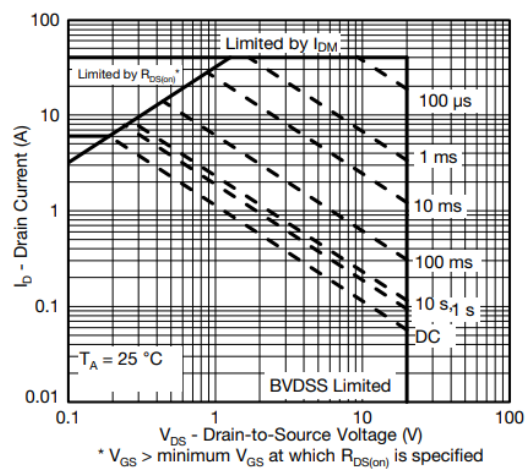
On-Resistance vs. Drain Current



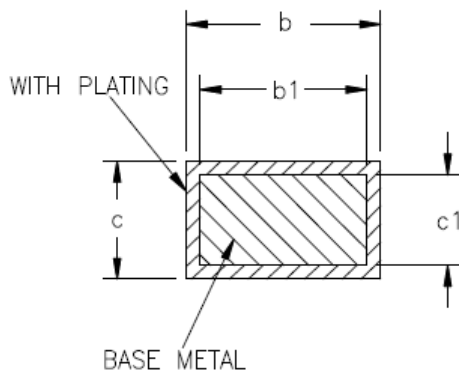
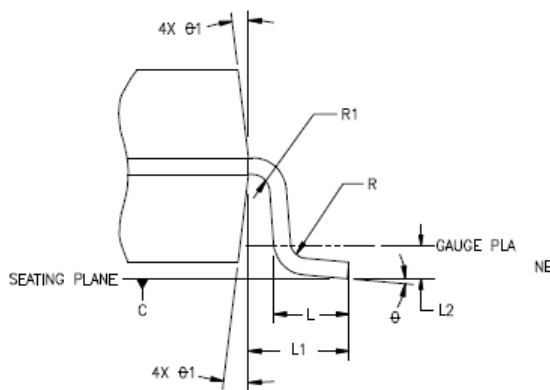
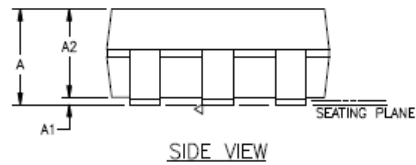
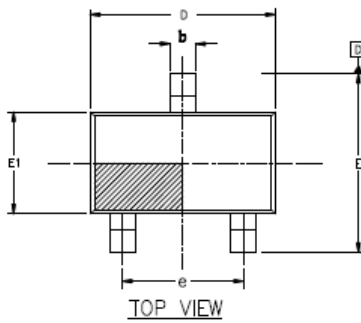
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



Safe Operating Area, Junction-to-Ambient

➤ Package Information


SYMBOL	MIN	NOM	MAX
A	--	--	1.35
A1	0	--	0.15
A2	1.0	1.1	1.2
b	0.35	--	0.45
b1	0.32	--	0.38
c	0.14	--	0.20
c1	0.14	0.15	0.16
D	2.82	2.92	3.02
E	2.60	2.80	3.00
E1	1.526	1.626	1.726
e	1.8	1.9	2.0
L	0.35	0.45	0.6
L1	0.6REF		
L2	0.25REF		
R	0.1	--	--
R1	0.1	--	--
θ	0°	4°	8°
θ1	5°	10°	15°

NOTES:

1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-178
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH
3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH
4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.

SOT23-3L



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